TOSHIBA Field Effect Transistor Silicon N Channel MOS Type ( $L^2$ - $\pi$ -MOSV)

## 2SK2267

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

• 4 V gate drive

• Low drain–source ON resistance  $: R_{DS (ON)} = 8 \text{ m}\Omega \text{ (typ.)}$ 

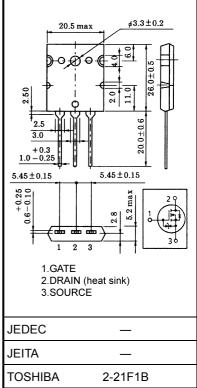
• High forward transfer admittance  $: |Y_{fs}| = 60 \text{ S (typ.)}$ • Low leakage current  $: I_{DSS} = 100 \,\mu\text{A (max)} \,(V_{DS} = 60 \,\text{V})$ 

• Enhancement-mode :  $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	60	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	60	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	60	Α	
	Pulse (Note 1)	$I_{DP}$	240	Α	
Drain power dissipation (Tc = 25°C)		$P_{D}$	150	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	1054	mJ	
Avalanche current		I <sub>AR</sub>	60	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	15	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

## Unit: mm



Weight: 9.75 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	0.833	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	35.7	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 25 V,  $T_{ch}$  = 25°C (initial), L = 398  $\mu$ H,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = 60 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.



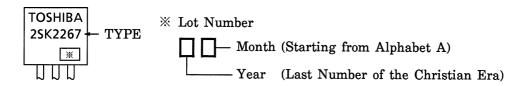
## **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	_	_	V
Gate threshold v	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	0.8	_	2.0	٧
Drain course ON registers		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 4 V, I <sub>D</sub> = 30 A	_	12	15	m0
Drain-source ON resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		_	8	11	mΩ	
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 30 A	40	60	_	S
Input capacitano	e	C <sub>iss</sub>		_	5400	_	
Reverse transfer capacitance		C <sub>rss</sub>		_	920	_	pF
Output capacitance		Coss		_	2600	_	
Switching time	Rise time	t <sub>r</sub>	V <sub>GS</sub> <sub>0V</sub> I <sub>D</sub> =30A OV <sub>OUT</sub> R <sub>L</sub> =1Ω	_	30	_	
	Turn-on time	t <sub>on</sub>		_	60	_	ns ns
	Fall time	t <sub>f</sub>		_	65	_	
	Turn-off time	t <sub>off</sub>	$V_{DD} = 30V$ Duty $\leq 1\%$ , $t_{W} = 10 \mu s$	_	220	_	
Total gate charg plus gate–drain)		Qg			170	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 60 \text{ A}$		110	_	nC
Gate-drain ("miller") charge		$Q_{gd}$			60	_	

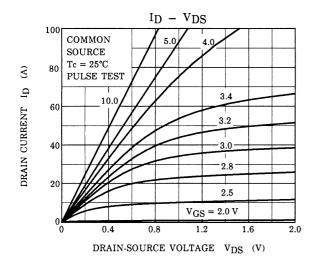
## Source-Drain Ratings and Characteristics (Ta = 25°C)

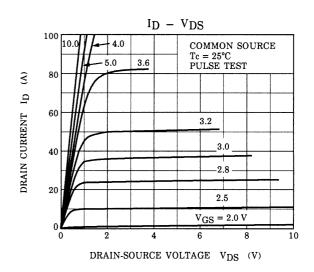
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	60	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	240	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 60 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 60 A, V <sub>GS</sub> = 0 V	_	150	_	ns
Reverse recovered charge	Q <sub>rr</sub>	dI <sub>DR</sub> / dt = 50 A / μs	_	0.3	_	μC

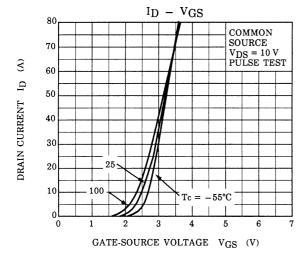
## Marking

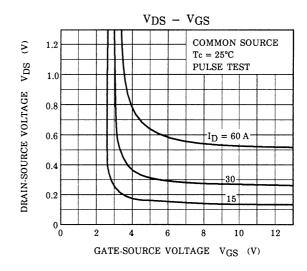


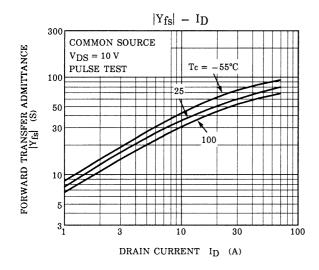
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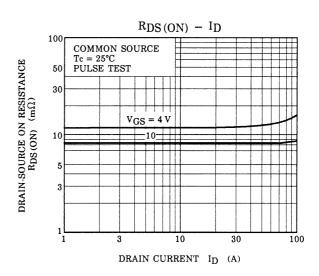




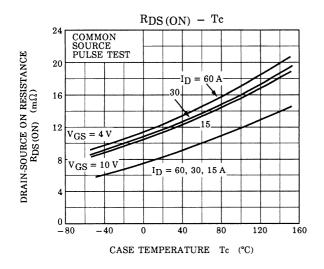


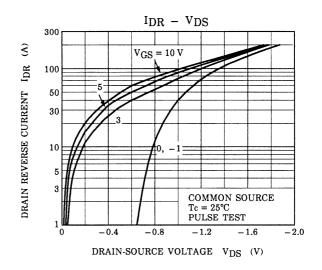


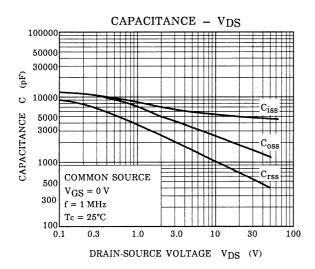


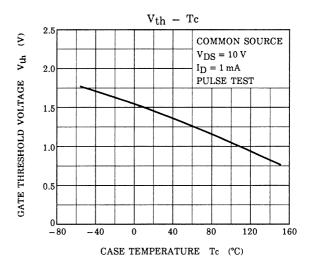


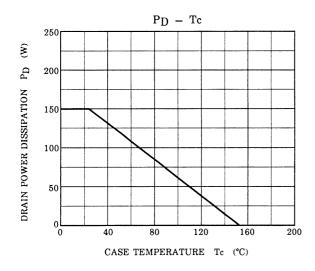
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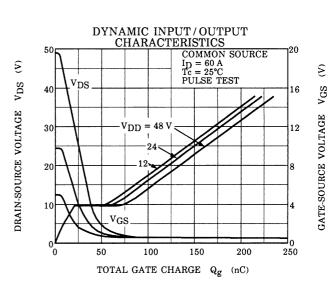




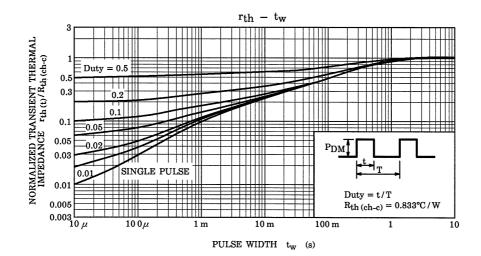


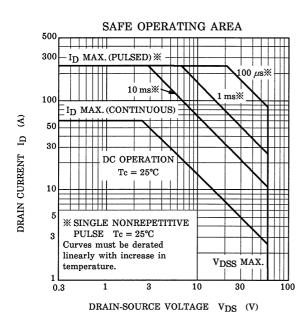


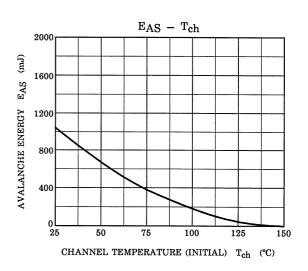


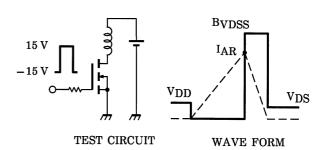


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$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 25~V,~L = 398~\mu H \end{aligned} \qquad EAS &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

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